

Title (en)

LAMINATED ASSEMBLY PROVIDED WITH LIGHT-EMITTING DIODES

Title (de)

LAMINIERTE ANORDNUNG MIT LEDS

Title (fr)

ASSEMBLAGE FEUILLETÉ AVEC DIODES LUMINESCENTES

Publication

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Application

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Abstract (en)

[origin: WO2007057454A1] The invention relates to a laminated assembly incorporating light emitting diodes comprising a first rigid film made of a dielectric material, an electric conductive circuit applied in the form of thin layers to the rigid film or to the thin non-conductive supporting film of said circuit, wherein said circuit supplies a plurality of light emitting diodes, at least one film made of a plastic non-conductive material uniformly covering the rigid film and diodes by enveloping said diodes and, possibly, a second rigid film adhered to the plastic material film. Said invention comprises at least one calendering operation for fixing films to each other and incorporating the diodes into the plastic material film.

IPC 8 full level

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